

CA3045, CA3046

General Purpose NPN Transistor Arrays

November 1996

Features

- Two Matched Transistors
- I_{IO} Match 2μA (Max)
- Low Noise Figure 3.2dB (Typ) at 1kHz
- 5 General Purpose Monolithic Transistors
- Operation From DC to 120MHz
- Wide Operating Current Range
- Full Military Temperature Range

Applications

- Three Isolated Transistors and One Differentially Connected Transistor Pair for Low Power Applications at Frequencies from DC Through the VHF Range
- Custom Designed Differential Amplifiers
- Temperature Compensated Amplifiers
- See Application Note, AN5296 "Application of the CA3018 Integrated-Circuit Transistor Array" for Suggested Applications

Description

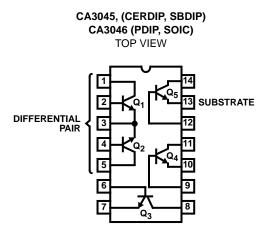
The CA3045 and CA3046 each consist of five general purpose silicon NPN transistors on a common monolithic substrate. Two of the transistors are internally connected to form a differentially connected pair.

The transistors of the CA3045 and CA3046 are well suited to a wide variety of applications in low power systems in the DC through VHF range. They may be used as discrete transistors in conventional circuits. However, in addition, they provide the very significant inherent integrated circuit advantages of close electrical and thermal matching.

Ordering Information

PART NUMBER (BRAND)	TEMP. RANGE (^o C)	PACKAGE	PKG. NO.	
CA3045	-55 to 125	14 Ld SBDIP	D14.3	
CA3045F	-55 to 125	14 Ld CERDIP	F14.3	
CA3046	-55 to 125	14 Ld PDIP	E14.3	
CA3046M (3046)	-55 to 125	14 Ld SOIC	M14.15	
CA3046M96 (3046)	-55 to 125	14 Ld SOIC Tape and Reel	M14.15	

Pinout



Absolute	Maximum	Ratings
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Operating Conditions

Thermal Information

5V	Thermal Resistance (Typical, Note 2)	θ _{JA} (^o C/W)	θ _{JC} (^o C/W)			
V	PDIP Package	180	N/A			
V	CERDIP Package	150	75			
5V	SBDIP Package	125	60			
۱A	SOIC Package	220	N/A			
) C	Maximum Power Dissipation (Any One Transistor)					

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

- The collector of each transistor of the CA3045 and CA3046 is isolated from the substrate by an integral diode. The substrate (Terminal 13) must be connected to the most negative point in the external circuit to maintain isolation between transistors and to provide for normal transistor action.
- 2. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications $T_A = 25^{\circ}C$, characteristics apply for each transistor in CA3045 and CA3046 as specified

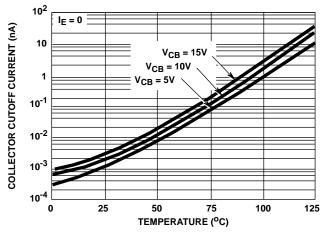
PARAMETER	SYMBOL	TEST C	ONDITIONS	MIN	ТҮР	MAX	UNITS
DC CHARACTERISTICS							
Collector-to-Base Breakdown Voltage	V _{(BR)CBO}	$I_{C} = 10\mu A, I_{E} = 0$		20	60	-	V
Collector-to-Emitter Breakdown Voltage	V _{(BR)CEO}	I _C = 1mA, I _B = 0		15	24	-	V
Collector-to-Substrate Breakdown Voltage	V _{(BR)CIO}	I _C = 10μΑ, I _{CI}	= 0	20	60	-	V
Emitter-to-Base Breakdown Voltage	V _{(BR)EBO}	I _E = 10μA, I _C	= 0	5	7	-	V
Collector Cutoff Current (Figure 1)	I _{CBO}	V _{CB} = 10V, I _E	= 0	-	0.002	40	nA
Collector Cutoff Current (Figure 2)	I _{CEO}	V _{CE} = 10V, I _B	= 0	-	See Fig. 2	0.5	μΑ
Forward Current Transfer Ratio (Static Beta) (Note 3) (Figure 3)	h _{FE}	V _{CE} = 3V	I _C = 10mA	-	100	-	-
			I _C = 1mA	40	100	-	-
			I _C = 10μΑ	-	54	-	-
Input Offset Current for Matched Pair Q_1 and Q_2 . $ I_{IO1} - I_{IO2} $ (Note 3) (Figure 4)		$V_{CE} = 3V, I_C = 1mA$		-	0.3	2	μA
Base-to-Emitter Voltage (Note 3) (Figure 5) V _{BE}	V _{BE}	V _{CE} = 3V I _E = 7	I _E = 1mA	-	0.715	-	V
			I _E = 10mA	-	0.800	-	V
Magnitude of Input Offet Voltage for Differential Pair $ V_{BE1} - V_{BE2} $ (Note 3) (Figures 5, 7)		V _{CE} = 3V, I _C = 1mA		-	0.45	5	mV
Magnitude of Input Offset Voltage for Isolated Transistors $ V_{BE3} - V_{BE4} $, $ V_{BE4} - V_{BE5} $, $ V_{BE5} - V_{BE3} $ (Note 3) (Figures 5, 7)		V _{CE} = 3V, I _C = 1mA		-	0.45	5	mV
Temperature Coefficient of Base-to-Emitter Voltage (Figure 6)	$\frac{\Delta V_{BE}}{\Delta T}$	$V_{CE} = 3V$, $I_C = 1mA$		-	-1.9	-	mV/ ^o C
Collector-to-Emitter Saturation Voltage	V _{CES}	I _B = 1mA, I _C = 10mA		-	0.23	-	V
Temperature Coefficient: Magnitude of Input Offset Voltage (Figure 7)	$\frac{\left \Delta V_{IO}\right }{\Delta T}$	$V_{CE} = 3V, I_C = 1mA$		-	1.1	-	μV/ ^o C

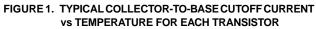
PARAMETER	SYMBOL TEST CONDITIONS		MIN	ТҮР	МАХ	UNITS
DYNAMIC CHARACTERISTICS						
Low Frequency Noise Figure (Figure 9)	NF	$\label{eq:constant} \begin{array}{l} f=1kHz, V_{CE}=3V, I_{C}=100\mu A,\\ \text{Source Resistance}=1k\Omega \end{array}$	-	3.25	-	dB
Low Frequency, Small Signal Equivalent Circuit Characteristics						
Forward Current Transfer Ratio (Figure 11)	h _{FE}	f = 1kHz, V_{CE} = 3V, I_C = 1mA	-	110	-	-
Short Circuit Input Impedance (Figure 11)	h _{IE}	f = 1kHz, V_{CE} = 3V, I_C = 1mA	-	3.5	-	kΩ
Open Circuit Output Impedance (Figure 11)	h _{OE}	f = 1kHz, V_{CE} = 3V, I_C = 1mA	-	15.6	-	μS
Open Circuit Reverse Voltage Transfer Ratio (Figure 11)	h _{RE}	$f = 1kHz$, $V_{CE} = 3V$, $I_C = 1mA$	-	1.8 x 10 ⁻⁴	-	-
Admittance Characteristics						
Forward Transfer Admittance (Figure 12)	Y _{FE}	f = 1kHz, V_{CE} = 3V, I_C = 1mA	-	31 - j1.5	-	-
Input Admittance (Figure 13)	Υ _{IE}	f = 1kHz, V_{CE} = 3V, I_C = 1mA	-	0.3 + j0.04	-	-
Output Admittance (Figure 14)	Y _{OE}	f = 1kHz, V_{CE} = 3V, I_C = 1mA	-	0.001 + j0.03	-	-
Reverse Transfer Admittance (Figure 15)	Y _{RE}	f = 1kHz, V_{CE} = 3V, I_C = 1mA	-	See Fig. 14	-	-
Gain Bandwidth Product (Figure 16)	f _T	$V_{CE} = 3V, I_C = 3mA$	300	550	-	MHz
Emitter-to-Base Capacitance	C _{EB}	$V_{EB} = 3V, I_{E} = 0$	-	0.6	-	pF
Collector-to-Base Capacitance	C _{CB}	$V_{CB} = 3V, I_{C} = 0$	-	0.58	-	pF
Collector-to-Substrate Capacitance	C _{CI}	$V_{CS} = 3V, I_{C} = 0$	-	2.8	-	pF

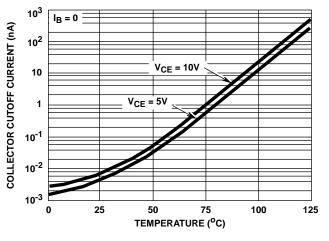
NOTE:

3. Actual forcing current is via the emitter for this test.

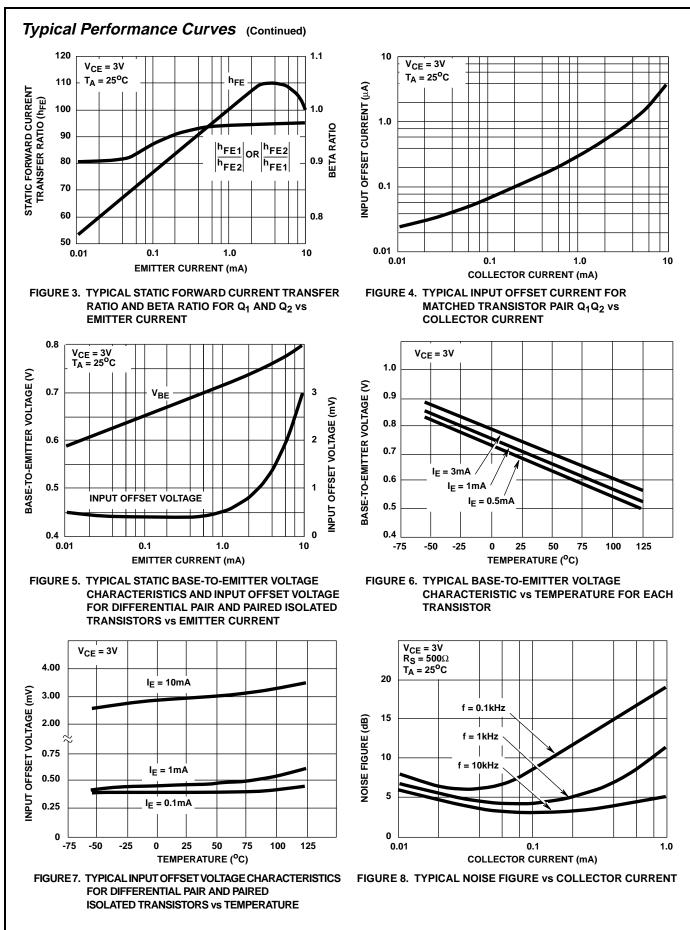
Typical Performance Curves

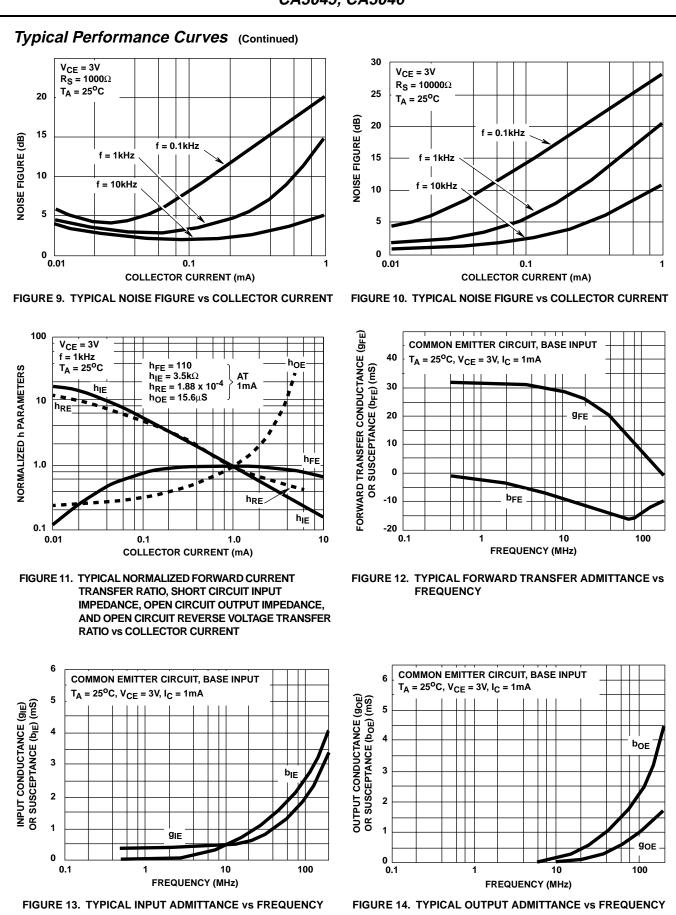


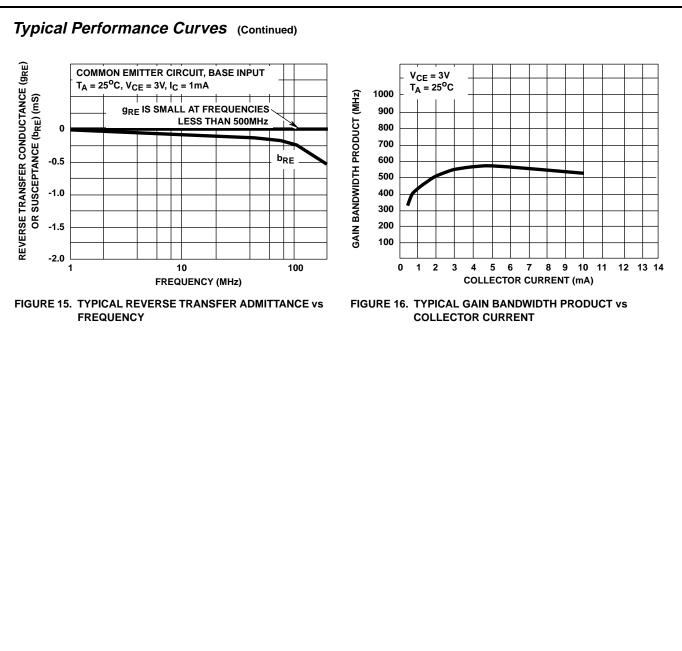












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